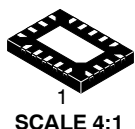


MECHANICAL CASE OUTLINE

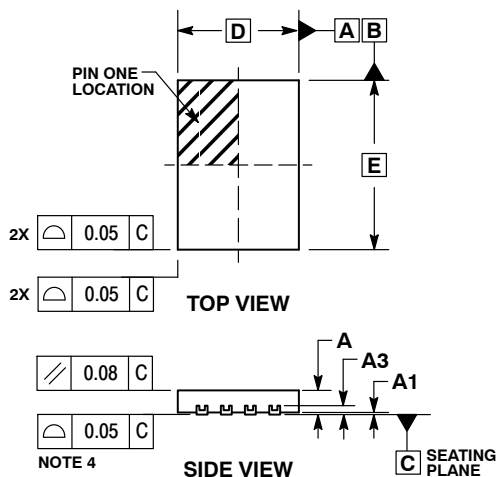
PACKAGE DIMENSIONS

ON Semiconductor®



X2QFN18, 2.0x2.8, 0.4P
CASE 722AB
ISSUE O

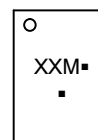
DATE 17 MAY 2016



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25 MM FROM THE TERMINAL TIP.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
A3	0.13	REF
b	0.13	0.23
D	2.00 BSC	
D2	0.90	1.00
E	2.80 BSC	
E2	1.70	1.80
e	0.40 BSC	
L	0.25	0.35
L2	0.11 REF	
L3	0.14 REF	

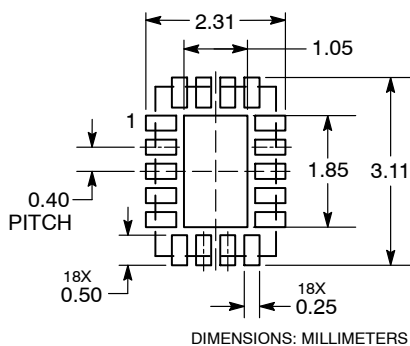
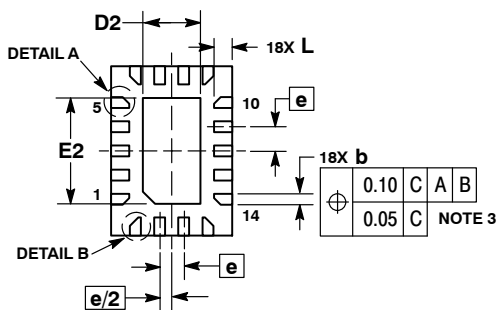
GENERIC MARKING DIAGRAM*



- XX = Specific Device Code
- M = Month Code
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	X2QFN18, 2.0 X 2.8, 0.4P	PAGE 1 OF 1

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